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TU-AM-2 TC6 Spectrum Management

Chair: Karen Dyberg, Raytheon Integrated Defense Systems, Sudbury, MA, USA

TU-AM-3 TC11 Nanotechnology and Advanced Materials

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TU-AM-6-SIPI SI/PI Advanced Noise/Jitter Modeling and Analysis

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Chair: Ross Carlton, National Instruments, Austin, TX, USA

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TU-PM-4 Special Session: TC11 Nanotechnology in EMC

Chair: Alessio Tamburrano, Sapienza University of Rome, Rome, Italy
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TU-PM-6-SIPI SI/PI High Speed Interconnect Design and Analysis I

Chair: Antonio Orlandi, University of L'Aquila, L'Aquila, Italy
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Chair: Alistair Duffy, De Montfort University, Leicester, United Kingdom
Co-Chair: Andy Drozd, ANDRO Computational Solutions, LLC, Rome, NY, USA

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Chair: A. Ege Engin, San Diego State University, San Diego, CA, USA
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Wednesday, August 6, 2014

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Chair: William Radasky, Metatech Corporation, Goleta, CA, USA
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Chair: Alpesh Bhobe, Cisco Systems, Inc., San Jose, CA, USA
Co-Chair: Wilson Wu, Shenzhen Sunway Communication Co., Ltd., Shenzhen, China

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Chair: Er-Ping Li, Zhejiang University, Hangzhou, China
Co-Chair: Antonio Ciccomancini, CST of America, Framingham, MA, USA

WED-PM-6-SIPI SI/PI High Speed Interconnect Design and Analysis II

Chair: Chunfei Ye, Intel Corporation, DuPont, WA, USA
Co-Chair: Changwook Yoon, Missouri University of Science and Technology, Rolla, MO, USA

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Chair: Don Heirman, Don HEIRMAN Consultants, Lincroft, NJ, USA

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Chair: Kai Xiao, Intel Corporation, Dupont, WA, USA
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Chair: Yu-ichi Hayashi, Tohoku University,Sendai, Japan
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Chair: Vignesh Rajamani, Oklahoma State University, Stillwater, OK, USA
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Finalist for Best SI/PI Paper Award

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TH-AM-5B-SIPI SI/PI High Speed Interconnect Design and Analysis III

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Finalist for Best SI/PI Paper Award

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Chair: Alan Roden, Aerospace Corporation, Chantilly, VA, USA
Co-Chair: Albert E. Ruehli, Missouri University of Science and Technology, Rolla, MO, USA

TH-PM-2 TC2 TEM and Reverb Measurements

Chair: Galen Koepke, National Institute of Standards and Technology, Boulder, CO, USA

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Andy Griffin *(Cisco Systems Inc., San Jose, CA, USA)*
Finalist for Best EMC Paper Award

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Co-Chair: Michael Cracraft, IBM Corporation, Poughkeepsie, NY, USA

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Finalist for Best Student SI/PI Paper Award
Finalist for Best SI/PI Paper Award

TH-PM-6-SIPI SI/PI High Speed Interconnect Design and Analysis IV

Chair: Venkatesh Seetharam, Avago Technologies, San Jose, CA, USA
Co-Chair: Olena Zhu, Intel Corporation, Santa Clara, CA, USA